

ABSTRACT OF THE DISCLOSURE

A semiconductor package for three-dimensional mounting is provided. The package includes a wiring substrate having a first surface on which a first wiring pattern is formed and a second surface on which a second wiring pattern is formed, the first wiring pattern and second wiring pattern being electrically connected to each other; a semiconductor chip placed on the first surface of the wiring substrate and electrically connected to the first wiring pattern; a sealing resin layer sealing the semiconductor chip and the first wiring pattern; a thickness direction wire passing through the sealing resin layer in a thickness direction and having one end electrically connected to the first wiring pattern and the other end exposed at the surface of the sealing resin layer; and a lower surface connecting electrode formed on the second surface of the wiring substrate and electrically connected to the second wiring pattern.

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